



S/N 10/815,464

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Todd B Myers et al.

Examiner: Thiem Phan

Serial No.: 10/815,464

Group Art Unit: 3729

Filed: March 31, 2004

Docket No.: 884.B60US1

Title: METHOD OF EMBEDDING PASSIVE
COMPONENT WITHIN VIA (as amended)

Assignee: Intel Corporation

Customer Number: 21186

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

This responds to the Office Action mailed on February 28, 2006. Please amend the
above-identified patent application as follows.

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Assignee: Intel Corporation

IN THE TITLE

Please amend the title as follows:

METHOD OF EMBEDDING PASSIVE COMPONENT WITHIN VIA